



QFN/DFN Assembly Generic QC Flow & Control Plan

Process Flow	Operation	Function	Frequency	Sample size
	Wafer mount	Visual check	Every wafer	Whole area of wafer back
	Wafer saw	Visual check	1x/shift/every change device	50 units
		Saw Line	Between 5th to 15th line in wafer	Every wafer
	Die Attach	Bond line thickness	Every set-up/change of device/conversion or 1xShift per machine	Min 2 units
		Visual check	Every magazine	Min 1 leadframe strip
		Die Shear test	1x/shift/machine	4 units
		Die Placement measurement	Every set-up/change of device/conversion or 1xShift per machine	Min 3 units
	Wire Bond	Bonding check	Start every lot / Beginning of shift	1 time
		Visual check	Every magazine	Min 1 strip / mag & 24 units / strip
		Wire pull test	1x/shift/machine	10 wires
		Ball shear test	1x/shift/machine	10 wires
		QA Visual check	Every set-up	1 unit
	Mold	X-Ray monitoring	min 1x/shift/machine	min 1 mold shot
		Visual check	min 1x/shift/machine	1 mold shot
	Laser marking	Visual check	Every subplot	1 lead frame strip
	Deflashing	Visual check	6x/shift	Min 1 strip
	Package saw singulation	Visual check	1x/sublot/machine	2 strips
		SPC buy-off	2x/shift/machine	8 units
		Package dim	2x/shift/machine	8 units

Test Generic QC Flow & Control Plan

Process Flow	Process	Function	Frequency	Sample size
	Electrical Test	EQA buyoff	Every lot	per AQL sampling plan, min 0.065
		OQA	Visual defects	Every lot
	Pack	Document, label	Every lot	